



# Product summary

## Travelstar 14GS

### AT/IDE



Model: DCYA-214000

---

#### Introducing

IBM's latest 2.5 inch disk drive provides 14,130MB in a slim 17mm package. The latest GMR head technology, IBM's patented No-ID sector formatting, the S.M.A.R.T. function, advanced power saving modes, and IBM's "Load/unload heads" technology make the Travelstar 14GS particularly suited to the mobile computing market and multimedia applications.

---

#### Applications

- High performance portable computers
- Non-IT - process control/fax
- Removable/secure storage units

---

#### Features

- 14,130MB at 512 bytes/sector
- Enhanced IDE interface with Ultra-DMA data transfer - mode 2 (33.3MB/sec)
- PIO data transfer - mode 4 (16.6MB/sec)
- Shock 400G (2ms) non-operational
- Shock 125G (2ms) operational
- 76.6 to 125.5 Mbits/sec media data transfer rate
- Rotational speed 4900 RPM
- Average seek time 12ms (read)
- Average latency 6.1ms
- Giant Magnetoresistive heads
- No-ID sector formatting
- PRML data channel
- 420KB segmented buffer with write cache
- Enhanced ECC On-The-Fly
- Adaptive power save control (0.85 Watt at idle state)
- Load/Unload heads
- S.M.A.R.T. function
- Drive Fitness Test (DFT) technology

---

#### Benefits

- High capacity in slim 2.5 inch form factor
- Popular interface with excellent performance
- Robust design for portable computing applications
- Excellent data rate across disk surface
- Fast access to data
- High areal density, low component count
- More data stored per track, increased sustained data transfer rate
- Fast access to data and improved throughput
- High reliability
- Low power for battery powered applications
- Increased durability during power save modes and non-operation
- Protection of user data

**Electrical connector locations**

**Drive Address**

Jumper positions to determine the drive address are available at the interface connector. The diagram at the bottom of this page reflects jumper pin location.

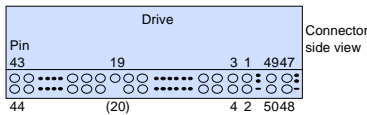
When using Cable Selection, the drive address depends on the condition of pin 28 of the AT interface cable. If pin 28 is ground or low, the drive is a Master. If pin 28 is open or high level, the drive is a Slave.

**Cabling**

The maximum cable length from the host system to the drive plus the length of the circuit pattern in the host system shall not exceed 18 inches.

**AT Signal Connector**

The AT signal connector is designed to mate with Dupont part number 69764-044 or equivalent.



**Data organization**

**DCYA-214000**

|                                    |                |
|------------------------------------|----------------|
| Head number                        | 16             |
| Sectors/track                      | 63             |
| Number of logical cylinders        | 16,383         |
| Sector size                        | 512            |
| Total customer usable data sectors | 27,609,120     |
| Total customer usable data bytes   | 14,135,869,440 |

**DC power requirements**

|  |                                     |
|--|-------------------------------------|
| Nominal supply                           | +5 Volt                             |
| Power supply ripple <sup>1</sup>         | 100 mV p-p max                      |
| Tolerance <sup>2</sup>                   | +/-5%                               |
| Supply wattage (+5.00 V case)            | Population mean (Nominal condition) |
| Performance idle average <sup>3</sup>    | 2.0 W typical                       |
| Active idle average                      | 1.3 W typical                       |
| Low power idle average                   | 0.85 W typical                      |
| Read <sup>4</sup>                        | 2.5 W typical                       |
| Write                                    | 2.7 W typical                       |
| Seek average <sup>5</sup>                | 2.6 W typical                       |
| Standby                                  | 0.25 W typical                      |
| Sleep                                    | 0.1 W typical                       |
| Startup (maximum peak) <sup>6</sup>      | 5.0 W typical                       |
| Startup (average from power on to ready) | 3.8 W typical                       |
| Supply rise time                         | 7 - 100 ms                          |

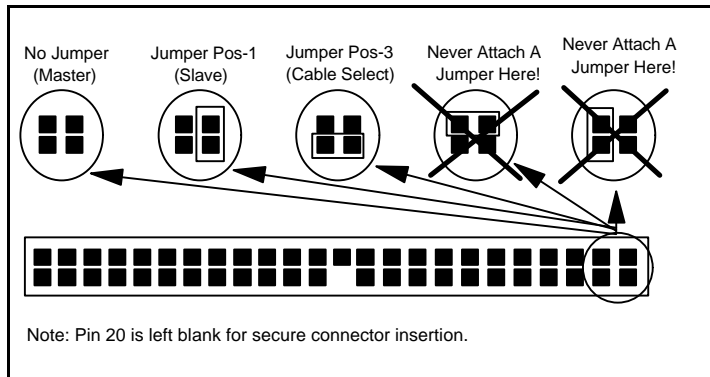
**Notes**

1. The maximum fixed disk ripple is measured at 5V input of the drive.
2. The disk drive shall not incur damage for an over voltage condition of +25% (maximum duration of 20 ms) on the 5 volt nominal supply.
3. The idle current is specified at an inner track.
4. The read/write current is specified based on three operations of 63 sector read/write per 100 ms.
5. The seek average current is specified based on three operations per 100msec.
6. The worst case operating current includes motor surge.

**ATTENTION:** The drive must be protected against electrostatic discharge especially when being handled. The safest way to avoid damage is to put the drive in an anti-static bag before ESD wrist straps are removed.



Drives should only be shipped in approved containers. Severe damage can be caused to the drive if the packaging does not adequately protect against the shock levels induced when a box is dropped. Consult your IBM representative if you do not have an approved shipping container.



**Command descriptions**

The following commands are supported by the drive:

| Command                        | Code (Hex) | Protocol |
|--------------------------------|------------|----------|
| Check power mode               | E5         | 3        |
| Check power mode*              | 98         | 3        |
| Execute device diagnostic      | 90         | 3        |
| Flush cache                    | E7         | 3        |
| Format track                   | 50         | 2        |
| Format unit                    | F7         | 3+       |
| Identify device                | EC         | 1        |
| Identify device DMA            | EE         | 4        |
| Idle                           | E3         | 3        |
| Idle*                          | 97         | 3        |
| Idle immediate                 | E1         | 3        |
| Idle immediate*                | 95         | 3        |
| Initialize device parameters   | 91         | 3        |
| Read buffer                    | E4         | 1        |
| Read DMA (retry)               | C8         | 4        |
| Read DMA (no retry)            | C9         | 4        |
| Read long (retry)              | 22         | 1        |
| Read long (no retry)           | 23         | 1        |
| Read multiple                  | C4         | 1        |
| Read native max address        | F8         | 3        |
| Read sectors (retry)           | 20         | 1        |
| Read sectors (no retry)        | 21         | 1        |
| Read verify sectors (retry)    | 40         | 3        |
| Read verify sectors (no retry) | 41         | 3        |
| Recalibrate                    | 1x         | 3        |
| Security disable password      | F6         | 2        |
| Security erase prepare         | F3         | 3        |
| Security erase unit            | F4         | 2        |
| Security freeze lock           | F5         | 3        |
| Security set password          | F1         | 2        |
| Security unlock                | F2         | 2        |
| Seek                           | 7x         | 3        |
| Set features                   | EF         | 3        |
| Set max address                | F9         | 3        |
| Set multiple mode              | C6         | 3        |
| Sleep                          | E6         | 3        |
| Sleep*                         | 99         | 3        |
| SMART disable operations       | B0         | 3        |

|   |    |   |
|---|----|---|
| SMART enable/disable attribute autosave | B0 | 3 |
| SMART enable operations                 | B0 | 3 |
| SMART execute off-line immediate        | B0 | 3 |
| SMART read attribute values             | B0 | 1 |
| SMART read attribute thresholds         | B0 | 1 |
| SMART return status                     | B0 | 3 |
| SMART save attribute values             | B0 | 3 |
| Standby                                 | E2 | 3 |
| Standby*                                | 96 | 3 |
| Standby immediate                       | E0 | 3 |
| Standby immediate*                      | 94 | 3 |
| Write buffer                            | E8 | 2 |
| Write DMA (retry)                       | CA | 4 |
| Write DMA (no retry)                    | CB | 4 |
| Write long (retry)                      | 32 | 2 |
| Write long (no retry)                   | 33 | 2 |
| Write multiple                          | C5 | 2 |
| Write sectors (retry)                   | 30 | 2 |
| Write sectors (no retry)                | 31 | 2 |
| Write verify                            | 3C | 2 |

**Protocol**

- 1 PIO data IN command
- 2 PIO data OUT command
- 3 Non data command
- 4 DMA command
- + Vendor specific command

\* Alternate command codes for previously defined commands

**Signal definition**

The pin assignments of interface signals are listed as follows:

| Pin | Signal | I/O |
|-----|--------|-----|
| 1   | -RESET | I   |
| 2   | GND    |     |
| 3   | DD07   | I/O |
| 4   | DD08   | I/O |
| 5   | DD06   | I/O |
| 6   | DD09   | I/O |
| 7   | DD05   | I/O |
| 8   | DD10   | I/O |
| 9   | DD04   | I/O |
| 10  | DD11   | I/O |
| 11  | DD03   | I/O |

|     |              |       |
|-----|--------------|-------|
| 12  | DD12         | I/O   |
| 13  | DD02         | I/O   |
| 14  | DD13         | I/O   |
| 15  | DD01         | I/O   |
| 16  | DD14         | I/O   |
| 17  | DD00         | I/O   |
| 18  | DD15         | I/O   |
| 19  | GND          |       |
| -20 | KEY          |       |
| 21  | DMARQ        | O     |
| 22  | GND          |       |
| 23  | -DIOW(*)     | I     |
| 24  | GND          |       |
| 25  | -DIOR(*)     | I     |
| 26  | GND          |       |
| 27  | IORDY(*)     | O     |
| 28  | CSEL         | I     |
| 29  | -DMACK       | I     |
| 30  | GND          |       |
| 31  | INTRQ        | O     |
| 32  | -IOCS16 (**) | O     |
| 33  | DA01         | I     |
| 34  | -PDIAG       | I/O   |
| 35  | DA00         | I     |
| 36  | DA02         | I     |
| 37  | -CS0         | I     |
| 38  | -CS1         | I     |
| 39  | -DASP        | I/O   |
| 40  | GND          |       |
| 41  | +5V logic    | power |
| 42  | +5V motor    | power |
| 43  | GND          |       |
| 44  | (reserve)    |       |

**Notes**

- “O” designates an output from the drive.
- “I” designates an input to the drive.

“I/O” designates an input/output common.  
 “OD” designates Open-Drain output.  
 (\*) designates signal lines that are redefined during the Ultra DMA protocol to provide special functions. If the Ultra DMA transfer mode was previously chosen via SetFeatures, these lines change from the conventional to special definitions at the moment the Host decides to allow a DMA burst. The drive becomes aware of this change upon assertion of the -DMACK line. These lines revert back to their original definitions upon the deassertion of -DMACK at the termination of the DMA burst.  
 “Power” designates a power supply to the drive.  
 “Reserve” designates reserved pins which must be left unconnected.

|                 | Special definition (for Ultra DMA0) | Conventional definition |
|-----------------|-------------------------------------|-------------------------|
| Write operation | -DDMARDY<br>HSTROBE<br>STOP         | IORDY<br>-DIOR<br>-DIOW |
| Read operation  | -HDMARDY<br>DSTROBE<br>STOP         | -DIOR<br>IORDY<br>-DIOW |

**5V power**

There are two input pins for +5V power supply, “+5V Logic” and “+5V Motor”. “+5V Logic” is connected to the internal logic circuits and “+5V Motor” is connected to the spindle motor and motor driver.

“+5V Logic” can be turned on and off by an external switch circuit to reduce power consumption. In this mode, a voltage drop out due to the motor spin up current can be reduced by connecting the “+5V Motor” line directly into the system power source.

If the above power management option is used, all signal lines that will be electrically active in the host system while the drive is disconnected from the power line

shall be isolated by Three-State line drivers. Internal leakage through the ESD protection circuit may bring the Least Positive Up Level (LPUL) of the logic signal below specifications.

Use both lines in parallel for regular drive application.

**Load/Unload heads**

When used properly, the Load/Unload mechanism allows 300,000 cycles of starts and stops. The heads are unloaded by invoking one of the following commands:

SOFT RESET  
 STANDBY  
 STANDBY IMMEDIATE  
 SLEEP

It is also invoked as one of the idle modes. After a short period of inactivity the Adaptive Battery Life Extender power management will unload the heads to conserve energy. When the heads are unloaded, they rest in a small detent. To prevent the heads from being thrown off the ramp during angular acceleration, a bi-directional, normally open, mechanical latch engages with the actuator to keep it from turning in the head loading direction. This action causes a “rattle” sound to be heard which can be mistaken for loose parts.

**Adaptive Battery Life Extender**

The Adaptive Battery Life Extender (ABLE-2) provides power saving without performance degradation. ABLE-2 technology automatically determines the correct time to start removing power from the drive electronics.

Most software and operating systems make use of a disk drive in bursts. The Travelstar drives monitor the commands which are sent from the host to detect

patterns which indicate that a command sequence is finished by putting the drive into low overall power consumption and longer battery life with no loss in performance. If the host system changes the number or frequency of commands which it sends then the disk drive will adapt automatically to this new pattern.

This feature has three idle modes; Performance idle mode, Active idle mode, and Low Power idle mode.

**Operating modes**

To provide the greatest flexibility of operation with optimum performance and power consumption, the drive has a number of operating modes. These are defined below.

**Active mode**

While in active mode, the drive is performing a command, writing cached data to disk or filling a read ahead buffer.

**Performance idle**

During performance idle, the drive is spinning but is not performing a command. It can respond immediately if a new command is received. The transition from active mode to performance idle mode is controlled by the arrival and completion of commands from the host system.

**Active idle**

During active idle, the drive is spinning but is not performing a command. The drive has determined that the previous command sequence (group of associated commands) is complete. Some of the drive electronics have been

## IBM storage products

powered down but the drive can still respond to a new command within 40 milliseconds. The transition from performance idle to active idle is controlled by IBM's patented Adaptive Battery Life Extender technology.

### Low Power idle

During Low Power idle, the drive is spinning but is not performing a command. The drive has determined that the previous command sequence (group of associated commands) is complete. Some of the drive electronics have been powered down but the drive can still respond to a new command within about 300 milliseconds. The transition from performance idle to low power idle is controlled by IBM's patented Adaptive Battery Life Extender technology.

### Standby

While in Standby mode, the drive is not spinning and is not performing a command. All electronics except for the command interface are turned off. The transition to Standby is controlled by a programmable timer which is set by the host system using standard ATA commands. After receiving a new command, the drive will start spinning again and perform the command within 2 to 3 seconds (typically).

### Sleep

While in Sleep mode, the drive is not spinning and is not performing commands. All of the electronics are turned off. The transition to Sleep mode is controlled by a command which is sent by the host system. The transition from sleep can only be triggered by a reset.

---

### Electromagnetic compatibility

The drive meets the following worldwide EMC requirements when installed in a suitable enclosure and exercised with a

random accessing routine at the maximum data rate:

United States Federal Communications Commission (FCC) Rules and Regulations (Class B), Part 15.

This drive is certified for compliance to EC directive 89/336/EEC.

C-Tick Mark complies with Australian EMC standard, AS/NZS 3548 : 1995 Class B.

---

### Operating environment

The drive operates within its performance limits when the following environment is maintained. Product life calculations are based on the nominal environment for a typical application.

| Relative humidity    |                          |
|----------------------|--------------------------|
| Operating            | 8 to 90% non-condensing  |
| Non-operating        | 5% to 95% non-condensing |
| Wet bulb temperature |                          |
| Operating            | 29.4 °C non-condensing   |
| Non-operating        | 40 °C non-condensing     |
| Elevation            |                          |
| Operating            | -300 to 3,000 m (10Kft)  |
| Non-operating        | -300 to 12,000 m (40Kft) |
| Temperature          |                          |
| Operating            | 5 to 55 °C               |
| Non-operating        | -40 to 65 °C             |
| Temperature gradient | 20 °C/hour               |

### Air cooling requirement

The host system must provide sufficient air flow across the drive to maintain the temperature at less than 60 °C at the center of the top cover of the drive and below 63 °C at the center of the card of the drive.

### Operating shock

The drive will withstand, with no hard error, a 125G half-sine wave

shock pulse of 2ms duration or 10G for 11 ms.

### Non-operating shock

The drive will withstand, with no permanent damage or degradation in performance, a 120G half-sine wave shock pulse of 11 ms duration or 400G for 2 ms.

### Operating and non-operating vibration

Due to the complexity of this subject, we recommend that users contact the distributor to discuss how to perform the necessary measurements if they believe this to be an area which requires evaluation.

---

### S.M.A.R.T. function

The intent of Self-Monitoring, Analysis, and Reporting Technology (S.M.A.R.T.) is to protect user data and prevent unscheduled system downtime that may be caused by predictable degradation or fault of the device. By monitoring and storing critical performance and calibration parameters, S.M.A.R.T. devices employ sophisticated data analysis algorithms to predict the likelihood of near-term degradation or fault condition. By alerting the host system of a negative reliability status condition, the host system can warn the user of the impending risk of a data loss and advise the user of appropriate action. Since S.M.A.R.T. utilizes the internal device microprocessor and other device resources, there may be some small overhead associated with its operation. However, special care has been taken in the design of the S.M.A.R.T. algorithms to minimize the impact to host system performance.

Actual impact of S.M.A.R.T. overhead is dependent on the specific device design and the usage patterns of the host system. To further ensure minimal impact to the user, S.M.A.R.T. capable devices are shipped from the device manufacturer's factory with the S.M.A.R.T. feature disabled. S.M.A.R.T. capable devices can be enabled by the system OEMs at the time of system integration or in the field by after market products.

For further details refer to the drive specification.

**Mechanical data**

**Weight**

182 grams typical, 185 grams maximum.

| Dimensions | S.I. Metric          |
|------------|----------------------|
| Height     | 17.0mm + 0.0 / - 0.5 |
| Width      | 69.85mm ± 0.25       |
| Length     | 100.2mm ± 0.25       |

**Drive usage condition**

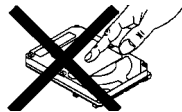
The drive is designed to be used under the following conditions:

- Levels of Shock, Vibration, Temperature, Humidity, Altitude, and Magnetic Field should be within the specifications.
- Measures should be taken against ESD.
- The breathing hole on top of the drive should not be covered.
- Pressure should not be applied to the top cover of the drive.
- The drive should be operated within the specification of less

than 140 power-on hours per month.

- Seeing, Writing, and Reading operation of the drive should be no more than 20% of power-on hours.
- The power requirements of the drive are to be satisfied.
- The drive frame is to be grounded electrically to the system by four screws.
- The drive should be mounted with the recommended screw depth and torque.
- Physical and electrical requirements of the interface are to be satisfied per ATA-4.
- The proper power off sequence should be used (see the drive specification for further details).

**Caution**

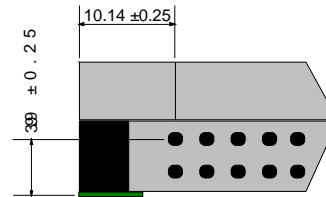
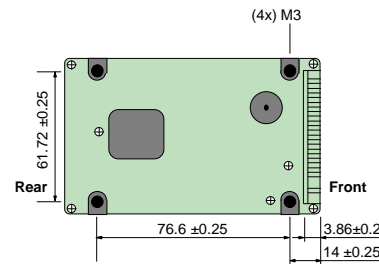
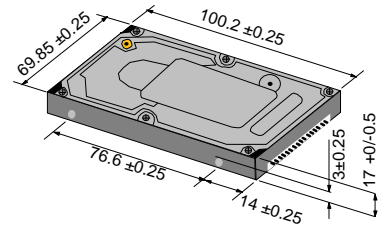


- Do not press on the drive during handling or installation.
- Do not cover the drive's breather hole.

**Mounting orientation**

The recommended mounting screw torque is  $3 \pm 0.5$ kgf.cm. The recommended mounting screw thread length is  $3.0 \pm 0.3$  mm for bottom and  $3.5 \pm 0.5$  mm for horizontal mounting.

The drive mounting hole locations and sizes are shown below.





© International Business Machines Corporation 2000

[www.ibm.com/harddrive](http://www.ibm.com/harddrive)

**IBM Hard Disk Drive Technical Support Center**

3605 Highway 52 North  
Rochester, MN 55901  
Telephone: 888.IBM.5214 or 507.286.5825  
Fax: 507.253.DRIVE  
E-mail: [drive@us.ibm.com](mailto:drive@us.ibm.com)

**Singapore Technical Support Center**

Telephone: (65)6418.9595 or 1800.418.9595  
E-mail: [drive@sg.ibm.com](mailto:drive@sg.ibm.com)

**IBM Storage Systems Division**

5600 Cottle Road  
San Jose, CA 95193  
[www.ibm.com/storage](http://www.ibm.com/storage)

Asia-Pacific Headquarters: 65.320.1234

European Headquarters: 44.01.705.561.871

Japan Sales Branch Office: 81.46645.1039

Printed in the United States of America  
04-2000  
All Rights Reserved

IBM, No-ID, and Predictive Failure Analysis are the registered trademarks of International Business Machines Corporation.

AMP is a trademark of AMP Incorporated.  
DATA MATE is a trademark of AMP Incorporated.  
Molex is a trademark of Molex Incorporated.

Other company, product, and service names may be trademarks or service marks of others.

Produced by the IBM Hard Disk Drive Technical Support Center.

OEM Hard Disk Drive Specifications for DCYA-21400, revision 0.2

This product summary is not a substitute for the full production specification, which should be used when detailed information is required.

Product Description data represents IBM's design objectives and is provided for comparative purposes; actual results may vary based on a variety of factors. This product data does not constitute a warranty. Questions regarding IBM's warranty terms or methodology used to derive this data should be referred to the IBM Hard Disk Drive Technical Support Center. Data subject to change without notice.

Date: 04 April 2000